

GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2013/06/14	Jamie Zie
A1			Add D/C	2016/01/07	Phebe Su
A2			Change the shape of the shell foot	2018/03/16	Summer Wang

NOTES:

- 1.MATERIAL:
HOUSING: HIGH TEMPERATURE THERMOPLASTIC
UL94V_0,COLOR:LCP(BLACK).
CONTACT: COPPER ALLOYS.T=0.2
COVER: COPPER ALLOYS OR STEEL. T=0.2.
- 2.PLATING:
UNDERPLATE: NICKEL 100U"MIN.
CONTACT AREA: GOLD(1U") OVER NICKEL 100U" MIN.
SOLDER AREA: TIN 100U" MIN OVER NICKEL 50U" MIN.
- 3.MULTIMEDIA CARD COMPATIBLE

MATRIX PART NO:

Matrix SIM

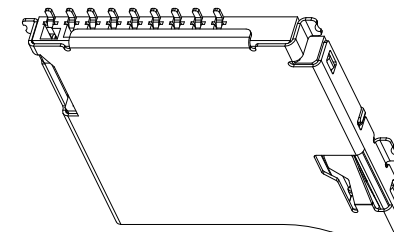
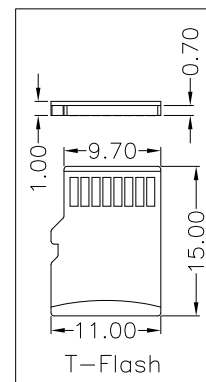
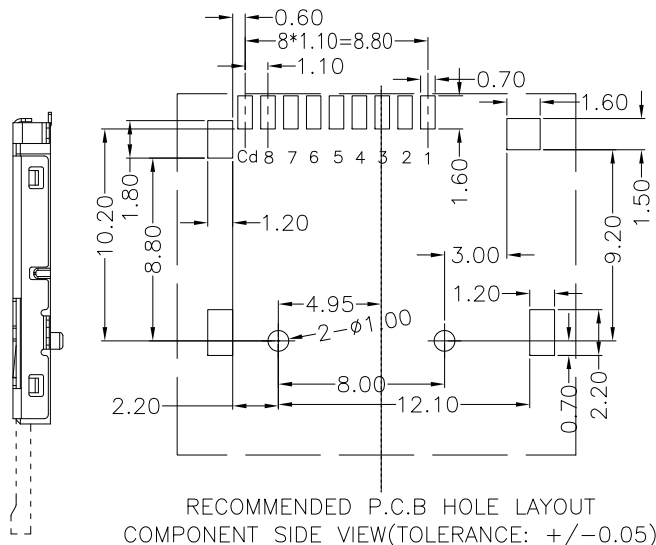
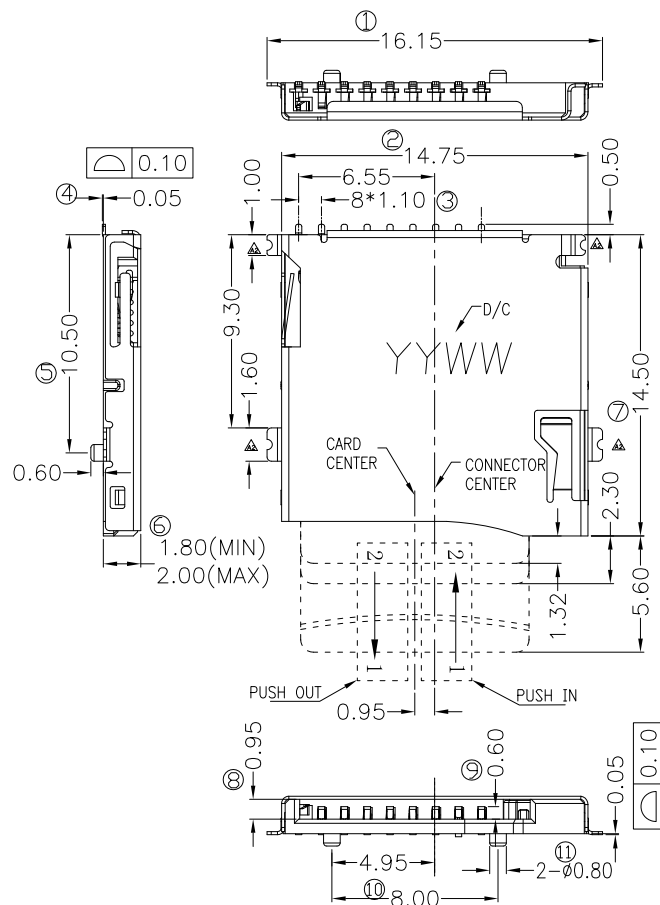
01 : Push
02 : Non-Push

Planting
01:G/F
30:30u

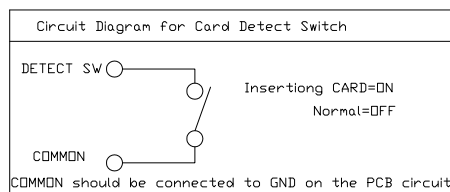
Pin number
06:6pin
08:8pin

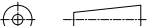
Series Number

01 - 01 - 08 - 20 - 06



PIN NO.	NAME	YYPE	DESCRIPTION
1	DAT2	I/O/PP	DATE LINE(BIT2)
2	CD/DAT3	I/O/PP	CARD DETECT DATE LIN(BIT3)
3	CMD	PP	COMMAND RESPONSE
4	VDD	S	SUPPLY VOLTAGE
5	CLX	I	CLOCK
6	VSS	S	SUPPLY VOLTAGE GROUND
7	DATO	I/O/PP	DATE LINE(BITO)
8	DAT1	I/O/PP	DATE LINE(DIT1)



NO	VARIETY	QTY	MATERIAL	REMARK	
 Matrix Electronics Co.,Ltd					
TOLERANCE: X.X ±0.20 X.XX ±0.15 X.XXX ±0.10 ANGLE: ±3°		DESIGN BY : Summer Wang	DATE : 2018/03/16	PART NAME: Micro SD push Outside welding	
		CHECKED BY: Vicky Hsieh	DATE : 2018/03/16	PART NO.	MMS-01-01-08-20-06
		APPROVED BY1: Richard Hsieh	DATE : 2018/03/16	MOLD NO.	NA
UNIT: mm [inch]		APPROVED BY2: Richard Hsieh	DATE : 2018/03/16	DRAW NO.	
SCALE:1:1	SIZE:A4			SHEET NO.	1 of 1